

# DRA3A43X

## Silicon PNP epitaxial planar type

For digital circuits

Complementary to DRC3A43X

DRA9A43X in SSSMini3 type package

### ■ Features

- Low collector-emitter saturation voltage  $V_{CE(sat)}$
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

### ■ Packaging

Embossed type (Thermo-compression sealing): 10000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

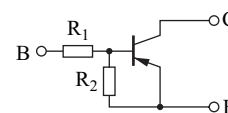
| Parameter                             | Symbol    | Rating      | Unit             |
|---------------------------------------|-----------|-------------|------------------|
| Collector-base voltage (Emitter open) | $V_{CBO}$ | -50         | V                |
| Collector-emitter voltage (Base open) | $V_{CEO}$ | -50         | V                |
| Collector current                     | $I_C$     | -80         | mA               |
| Total power dissipation               | $P_T$     | 100         | mW               |
| Junction temperature                  | $T_j$     | 150         | $^\circ\text{C}$ |
| Storage temperature                   | $T_{stg}$ | -55 to +150 | $^\circ\text{C}$ |

### ■ Package

- Code  
SSSMini3-F2-B
- Pin Name  
1: Base  
2: Emitter  
3: Collector

### ■ Marking Symbol: G9

### ■ Internal Connection



| Resistance value | $R_1$ | 4.7 | k $\Omega$ |
|------------------|-------|-----|------------|
|                  | $R_2$ | 10  | k $\Omega$ |

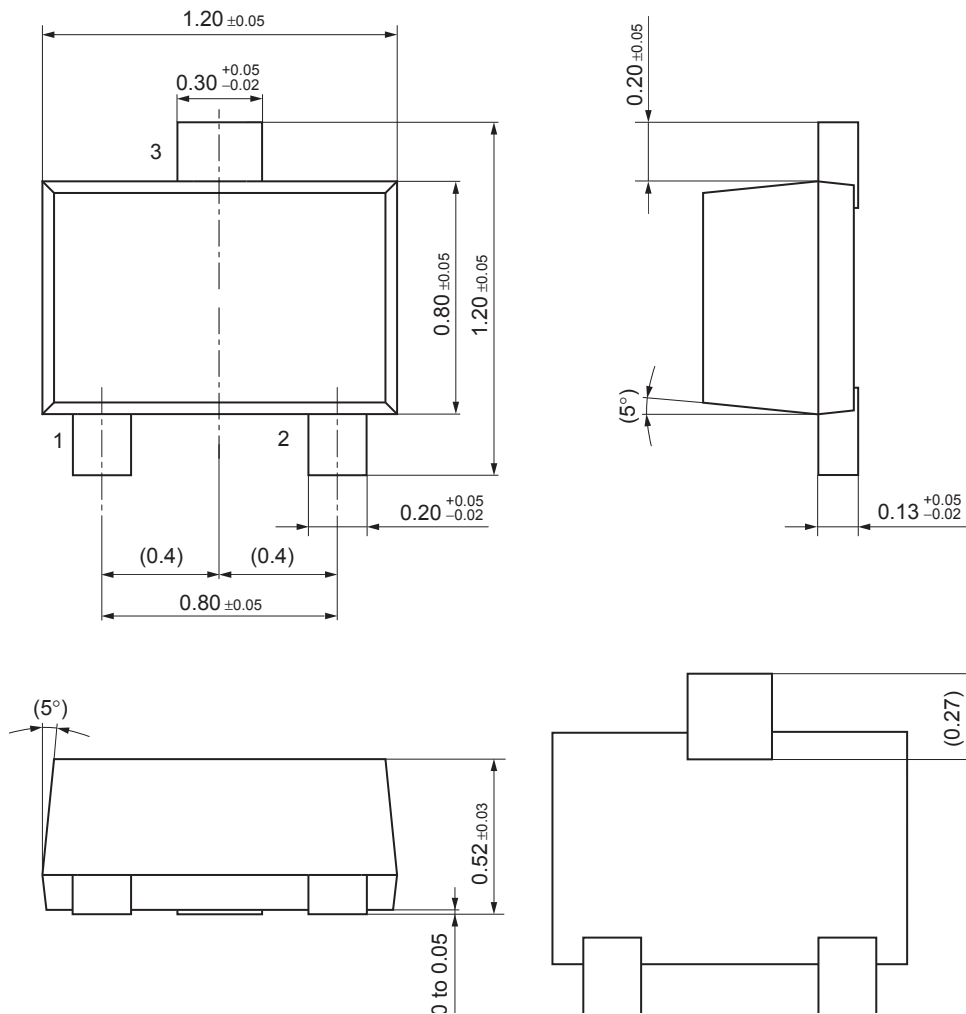
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter                                    | Symbol        | Conditions   | Min  | Typ  | Max   | Unit          |
|--|---------------|--|------|------|-------|---------------|
| Collector-base voltage (Emitter open)        | $V_{CBO}$     | $I_C = -10 \mu\text{A}$ , $I_E = 0$                | -50  |      |       | V             |
| Collector-emitter voltage (Base open)        | $V_{CEO}$     | $I_C = -2 \text{ mA}$ , $I_B = 0$                  | -50  |      |       | V             |
| Collector-base cutoff current (Emitter open) | $I_{CBO}$     | $V_{CB} = -50 \text{ V}$ , $I_E = 0$               |      |      | -0.1  | $\mu\text{A}$ |
| Collector-emitter cutoff current (Base open) | $I_{CEO}$     | $V_{CE} = -50 \text{ V}$ , $I_B = 0$               |      |      | -0.5  | $\mu\text{A}$ |
| Emitter-base cutoff current (Collector open) | $I_{EBO}$     | $V_{EB} = -6 \text{ V}$ , $I_C = 0$                |      |      | -1.0  | mA            |
| Forward current transfer ratio               | $h_{FE}$      | $V_{CE} = -10 \text{ V}$ , $I_C = -5 \text{ mA}$   | 30   |      |       | —             |
| Collector-emitter saturation voltage         | $V_{CE(sat)}$ | $I_C = -10 \text{ mA}$ , $I_B = -0.5 \text{ mA}$   |      |      | -0.25 | V             |
| Input voltage (ON)                           | $V_{I(on)}$   | $V_{CE} = -0.2 \text{ V}$ , $I_C = -5 \text{ mA}$  | -1.7 |      |       | V             |
| Input voltage (OFF)                          | $V_{I(off)}$  | $V_{CE} = -5 \text{ V}$ , $I_C = -100 \mu\text{A}$ |      |      | -0.6  | V             |
| Input resistance                             | $R_1$         |  | -30% | 4.7  | +30%  | k $\Omega$    |
| Resistance ratio                             | $R_1 / R_2$   |  | 0.37 | 0.47 | 0.57  | —             |

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

SSSMini3-F2-B

Unit: mm



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